



Product Change Notification: JPZA-02IUGE098

Date:

08-Sep-2026

Product Category:

Analog Multiplexer/Switch ICs, Equalizers, Transceivers, Ultrasound Transmitter Pulser ICs

Notification Subject:

CCB 8427.001 Initial Notice: Qualification of 558-2C31 as a new die attach material for selected HV2809, HV2808, HV7350, EQCO62R20, EQCO62T20, EQCO30T5, EQCO30R5, EQCO31T20 and EQCO31R20 device families available in 56L VQFN (8x8x1.0mm) and 16L QFN (4x4x0.9mm) packages at NSEB assembly site.

Affected CPNs:

[JPZA-02IUGE098_Affected_CPN_09082026.pdf](#)

[JPZA-02IUGE098_Affected_CPN_09082026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of 558-2C31 as a new die attach material for selected HV2809, HV2808, HV7350, EQCO62R20, EQCO62T20, EQCO30T5, EQCO30R5, EQCO31T20 and EQCO31R20 device families available in 56L VQFN (8x8x1.0mm) and 16L QFN (4x4x0.9mm) packages at NSEB assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change
Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	No
Wire Material	Au	Au	No

Die Attach Material	8600 (PFAS)	8200T (PFAS)	558-2C31 (PFAS-free)	Yes
Molding Compound Material	G770HCD		G770HCD	No
Lead-Frame Material	C194		C194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying 558-2C31 as a new die attach material at NSEB assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: April 2027

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	September 2026					>	December 2026				
Work Week	36	37	38	39	40		49	50	51	52	53
Initial PCN Issue Date		x									
Qual Report Availability											x
Final PCN Issue Date											x

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.
Note: This is a qualification by similarity (QBS) to CCB# 8427

Revision History: September 08, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach Explanation.pdf
PCN_JPZA-02IUUGE098 Qual Plan.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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